





### **N-CHANNEL ENHANCEMENT MODE MOSFET**

### **Features**

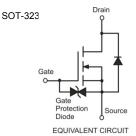
- Low On-Resistance
- Very Low Gate Threshold Voltage (1.0V max)
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected Up To 2kV
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 standards for High Reliability

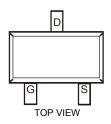
## **Mechanical Data**

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound.
  UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe.
  Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)









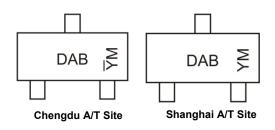
Ordering Information (Note 4)

Ī	Part Number	Case	Packaging
	DMN5L06WK-7	SOT-323	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

## **Marking Information**



DAB = Product Type Marking Code YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)  $\overline{Y}$ M = Date Code Marking for CAT (Chengdu Assembly/ Test site) Y or  $\overline{Y}$  = Year (ex: A = 2013) M = Month (ex: 9 = September)

### Date Code Key

Ye	ar	2012	2	2013		2014	20	15	2016		2017		2018
Co	de	Z		Α		В	(	$\circ$	D		E		F
Мо	nth	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Co	de	1	2	3	4	5	6	7	8	9	0	N	D



## **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

	Characteristic	Symbol	Value	Unit
Drain Source Voltage		$V_{DSS}$	50	V
Gate-Source Voltage		$V_{GSS}$	±20	V
Drain Current (Note 5)	Continuous	I <sub>D</sub>	300	mA
	Pulsed (Note 6)	_	800	

# **Thermal Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	$P_{D}$	250	mW
Thermal Resistance, Junction to Ambient	R <sub>0JA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

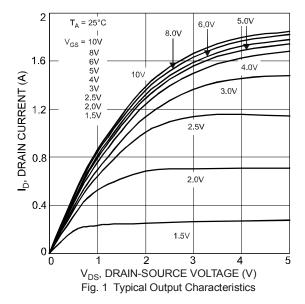
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

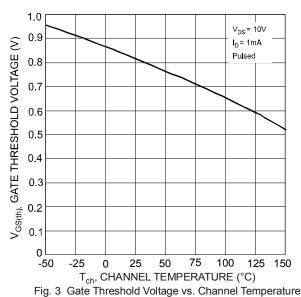
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	50	_	_	V	$V_{GS} = 0V, I_D = 10\mu A$
Zero Gate Voltage Drain Current	@T <sub>C</sub> = +25°C	I <sub>DSS</sub>	_	_	60	nA	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V
					1	μΑ	$V_{GS} = \pm 12V, V_{DS} = 0V$
Gate-Body Leakage		$I_{GSS}$	_		500	nA	$V_{GS} = \pm 10V$ , $V_{DS} = 0V$
					50	nA	$V_{GS} = \pm 5V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage		V <sub>GS(th)</sub>	0.49	—	1.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
		R <sub>DS (ON)</sub>	_	_	3.0	Ω	$V_{GS} = 1.8V, I_D = 50mA$
Static Drain-Source On-Resistance			_	_	2.5		$V_{GS} = 2.5V, I_D = 50mA$
			_	_	2.0		$V_{GS} = 5.0V, I_D = 50mA$
On-State Drain Current		I <sub>D(ON)</sub>	0.5	1.4	_	Α	$V_{GS} = 10V, V_{DS} = 7.5V$
Forward Transconductance		Y <sub>fs</sub>	200	_	_	mS	$V_{DS}$ =10V, $I_{D}$ = 0.2A
Source-Drain Diode Forward Voltage		$V_{SD}$	0.5	_	1.4	V	$V_{GS} = 0V, I_{S} = 115mA$
DYNAMIC CHARACTERISTICS (Note 8)		•				•	
Input Capacitance		C <sub>iss</sub>	_	_	50	pF	V 05V V 0V
Output Capacitance		Coss	_	_	25	pF	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V -f = 1.0MHz
Reverse Transfer Capacitance			_	_	5.0	pF	1 - 1.0IVII IZ
Turn-On Delay Time			_	2.1		ns	
Turn-On Rise Time			_	1.8	_	ns	$V_{DD} = 30V, V_{GS} = 10V,$
Turn-Off Delay Time			_	14.4		ns	$R_G = 25\Omega, I_D = 200 \text{mA}$
Turn-Off Fall Time	t <sub>f</sub>	_	8.4		ns		

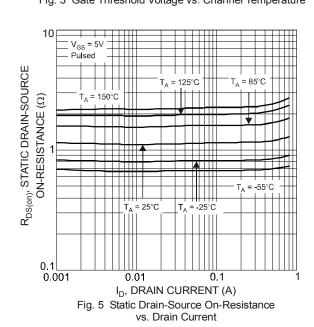
- Notes: 5. Device mounted on FR-4 PCB.

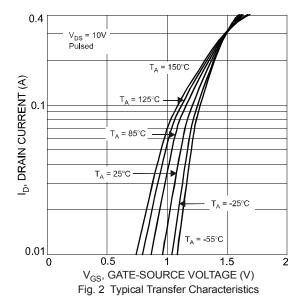
  - Pulse width ≤10µS, Duty Cycle ≤1%.
    Short duration pulse test used to minimize self-heating effect.
    Guaranteed by design. Not subject to production testing.











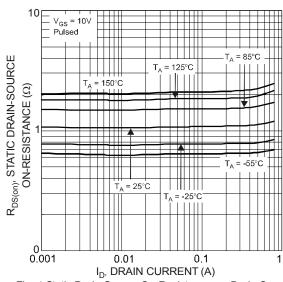
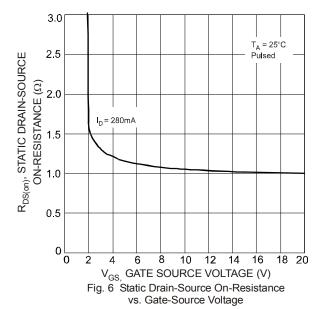


Fig. 4 Static Drain-Source On-Resistance vs. Drain Current





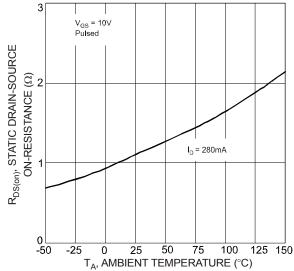


Fig. 7 Static Drain-Source On-State Resistance vs. Ambient Temperature

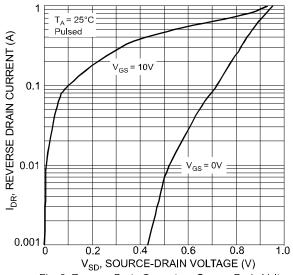
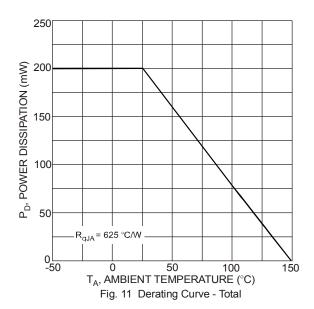


Fig. 9 Reverse Drain Current vs. Source-Drain Voltage



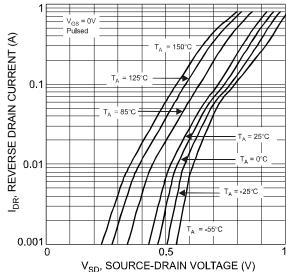


Fig. 8 Reverse Drain Current vs. Source-Drain Voltage

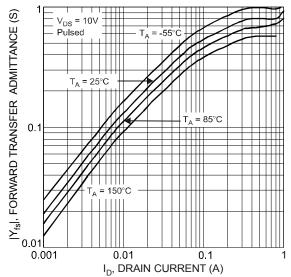
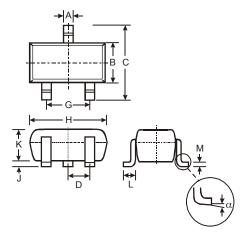


Fig. 10 Forward Transfer Admittance vs. Drain Current



## **Package Outline Dimensions**

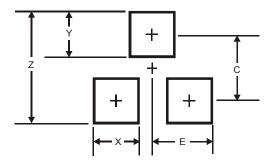
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT-323								
Dim	Min	Max	Тур					
Α	0.25	0.40	0.30					
В	1.15	1.35	1.30					
С	2.00	2.20	2.10					
D	-	1	0.65					
G	1.20	1.40	1.30					
Н	<b>H</b> 1.80		2.15					
J	0.0	0.10	0.05					
K	0.90	1.00	0.95					
L	0.25	0.40	0.30					
M	0.10	0.18	0.11					
α	0°	8°	-					
All	All Dimensions in mm							

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.8
X	0.7
Y	0.9
С	1.9
E	1.0



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